

SOT917-4

plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; body 4 mm x 4 mm x 0.85 mm

3 April 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN
Package type industry code	HVQFN20
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	7-11-2014
Manufacturer package code	SOT917

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	3.9	-	4	4.1	mm
A	seated height	0.8	-	0.85	1	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	20	-	



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2. Package outline

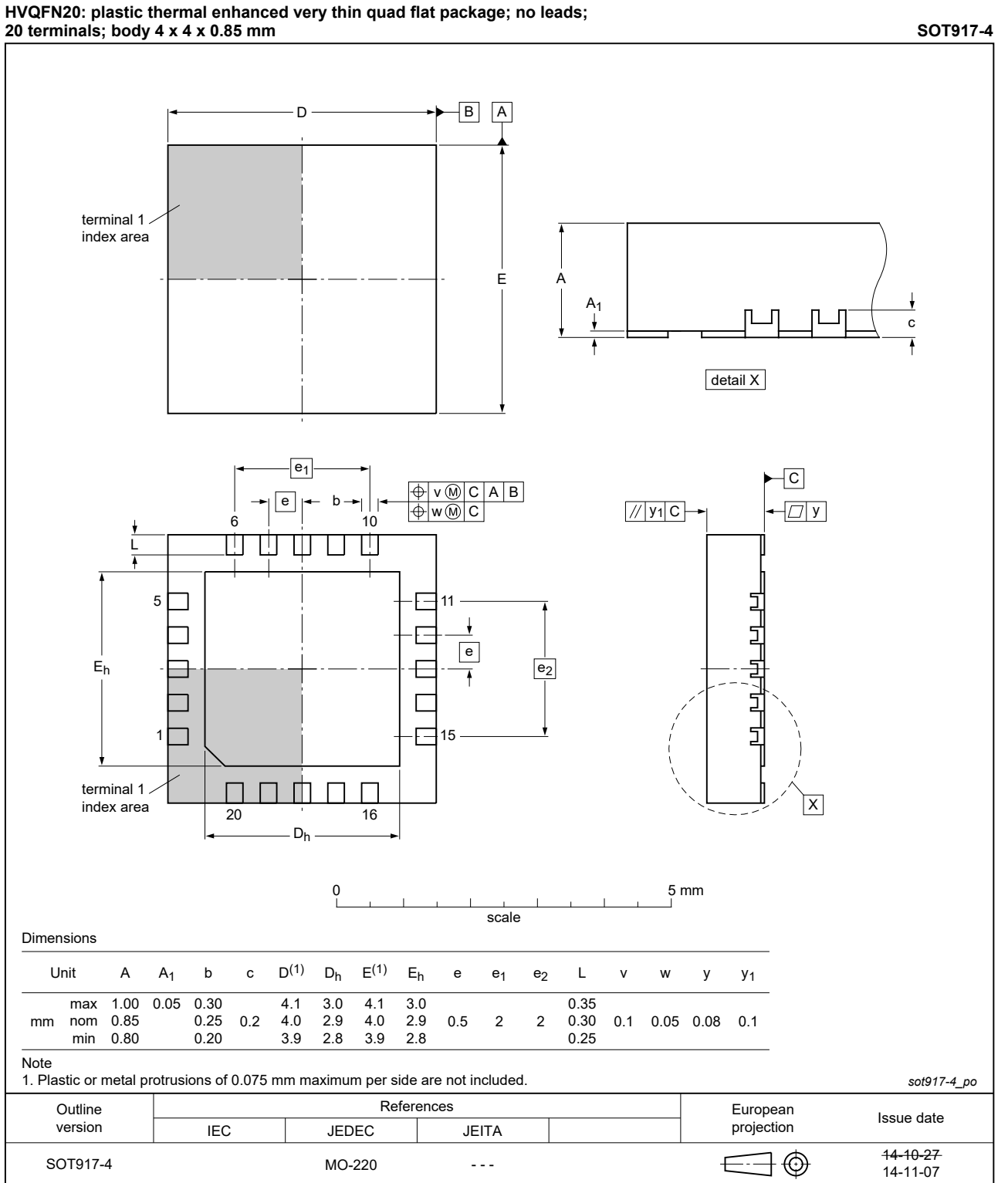


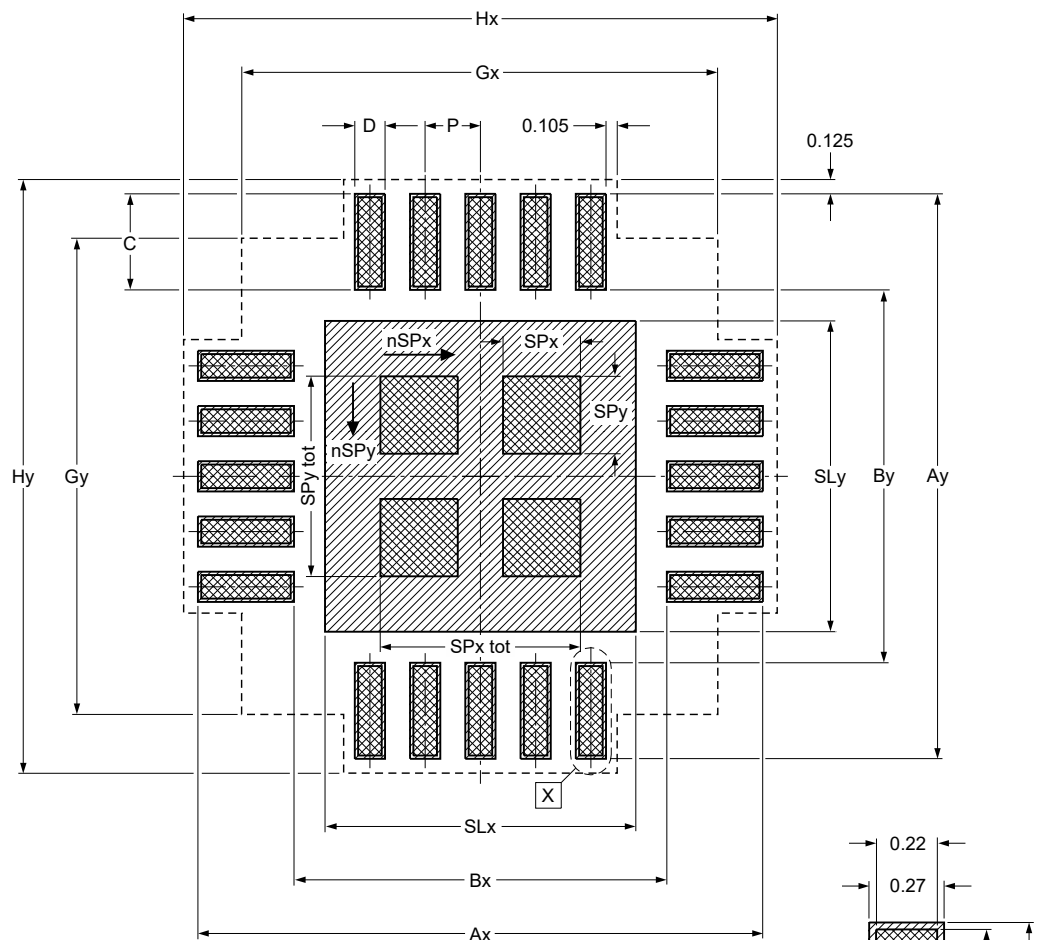
Fig. 1. Package outline HVQFN20 (SOT917-4)

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3. Soldering

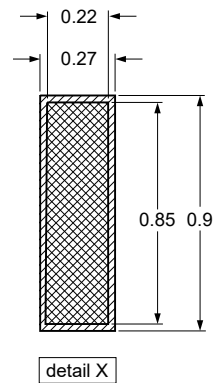
Footprint information for reflow soldering of HVQFN20 package

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Recommended stencil thickness: 0.1 mm

- solder land
 - solder land plus solder paste
 - solder paste deposit
 - solder resist
 - occupied area
- Dimensions in mm



Dimensions (mm are the original dimensions)

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy	nSPx	nSPy
0.5	5.1	5.1	3.4	3.4	0.85	0.27	2.8	2.8	1.8	1.8	0.7	0.7	4.3	4.3	5.35	5.35	2	2

Issue date ~~15-01-26~~
16-07-18

sot917-4_fr

Fig. 2. Reflow soldering footprint for HVQFN20 (SOT917-4)

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4. Legal information

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